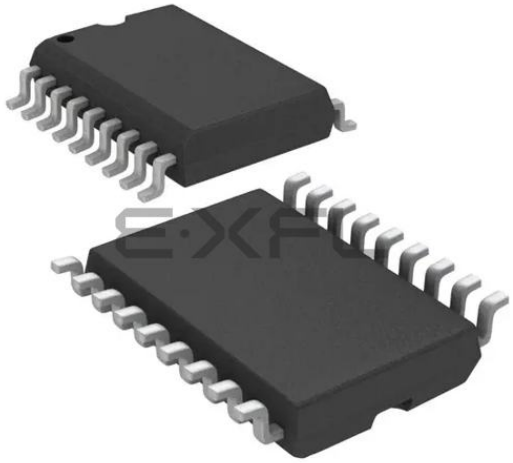


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c716-04-so

Key Features PIC® Mid-Range Reference Manual (DS33023)	PIC16C712	PIC16C716
Operating Frequency	DC – 20 MHz	DC – 20 MHz
Resets (and Delays)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)
Program Memory (14-bit words)	1K	2K
Data Memory (bytes)	128	128
Interrupts	7	7
I/O Ports	Ports A,B	Ports A,B
Timers	3	3
Capture/Compare/PWM modules	1	1
8-bit Analog-to-Digital Module	4 input channels	4 input channels

PIC16C7XX FAMILY OF DEVICES

		PIC16C710	PIC16C71	PIC16C711	PIC16C712	PIC16C715	PIC16C716	PIC16C72A	PIC16C73B
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	1K	2K	2K	2K	4K
	Data Memory (bytes)	36	36	68	128	128	128	128	192
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0 TMR1 TMR2	TMR0	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2
	Capture/Compare/ PWM Module(s)	—	—	—	1	—	1	1	2
	Serial Port(s) (SPI™/I^2C™, USART)	—	—	—	—	—	—	SPI/I^2C	SPI/I^2C, USART
	A/D Converter (8-bit) Channels	4	4	4	4	4	4	5	5
Features	Interrupt Sources	4	4	4	7	4	7	8	11
	I/O Pins	13	13	13	13	13	13	22	22
	Voltage Range (Volts)	2.5-6.0	3.0-6.0	2.5-6.0	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
	In-Circuit Serial Programming™	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral Modules for controlling the desired operation of the device. These registers are implemented as static RAM. A list of these registers is give in Table 2-1.

The Special Function Registers can be classified into two sets; core (CPU) and peripheral. Those registers associated with the core functions are described in detail in this section. Those related to the operation of the peripheral features are described in detail in that peripheral feature section.

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets (4)
Bank 0											
00h	INDF(1)	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 Module's Register								xxxx xxxx	uuuu uuuu
02h	PCL(1)	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h	STATUS(1)	IRP(4)	RP1(4)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	rr01 1xxx	rr0q quuu
04h	FSR(1)	Indirect Data Memory Address Pointer								xxxx xxxx	uuuu uuuu
05h	PORTA(5,6)	—	—	—(7)	PORTA Data Latch when written: PORTA pins when read					--xx xxxx	--xu uuuu
06h	PORTB(5,6)	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
07h	DATACCP	—(7)	—(7)	—(7)	—(7)	—(7)	DCCP	—(7)	DT1CK	xxxx xxxx	xxxx xuxu
08h-09h	—	Unimplemented								–	–
0Ah	PCLATH(1,2)	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh	INTCON(1)	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- 0000	-0-- 0000
0Dh	—	Unimplemented								–	–
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
11h	TMR2	Timer2 Module's Register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h-14h											
15h	CCPR1L	Capture/Compare/PWM Register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
18h-1Dh	—	Unimplemented								–	–
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{DONE}$	—	ADON	0000 00-0	0000 00-0

Legend: x = unknown, u = unchanged, q = value depends on condition, — = unimplemented, read as '0', Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for PC<12:8> whose contents are transferred to the upper byte of the program counter.

3: Other (non Power-up) Resets include: external Reset through $\overline{MCLR}$ and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved. Always maintain these bits clear.

5: On any device Reset, these pins are configured as inputs.

6: This is the value that will be in the port output latch.

7: Reserved bits; Do Not Use.

2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts.

Note:	Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7: **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6: **PEIE**: Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5: **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4: **IINTE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3: **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2: **T0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1: **INTF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0: **RBIF**: RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

TABLE 5-1: TMR1 MODULE AND PORTB OPERATION

TMR1 Module Mode	Clock Source	Control Bits	TMR1 Module Operation	PORTB<2:1> Operation
Off	N/A	T1CON = --xx 0x00	Off	PORTB<2:1> function as normal I/O
Timer	Fosc/4	T1CON = --xx 0x01	TMR1 module uses the main oscillator as clock source. TMR1ON can turn on or turn off Timer1.	PORTB<2:1> function as normal I/O
Counter	External circuit	T1CON = --xx 0x11 TR1SCCP = ---- -x-1	TMR1 module uses the external signal on the RB1/T1OSO/T1CKI pin as a clock source. TMR1ON can turn on or turn off Timer1. DT1CK can read the signal on the RB1/T1OSO/T1CKI pin.	PORTB<2> functions as normal I/O. PORTB<1> always reads '0' when configured as input. If PORTB<1> is configured as output, reading PORTB<1> will read the data latch. Writing to PORTB<1> will always store the result in the data latch, but not to the RB1/T1OSO/T1CKI pin. If the TMR1CS bit is cleared (TMR1 reverts to the timer mode), then pin PORTB<1> will be driven with the value in the data latch.
	Firmware	T1CON = --xx 0x11 TR1SCCP = ---- -x-0	DATACCP<0> bit drives RB1/T1OSO/T1CKI and produces the TMR1 clock source. TMR1ON can turn on or turn off Timer1. The DATACCP<0> bit, DT1CK, can read and write to the RB1/T1OSO/T1CKI pin.	
	Timer1 oscillator	T1CON = --xx 1x11	RB1/T1OSO/T1CKI and RB2/T1OSI are configured as a 2 pin crystal oscillator. RB1/T1OSI/T1CKI is the clock input for TMR1. TMR1ON can turn on or turn off Timer1. DATACCP<1> bit, DT1CK, always reads '0' as input and can not write to the RB1/T1OSO/T1CK1 pin.	PORTB<2:1> always read '0' when configured as inputs. If PORTB<2:1> are configured as outputs, reading PORTB<2:1> will read the data latches. Writing to PORTB<2:1> will always store the result in the data latches, but not to the RB2/T1OSI and RB1/T1OSO/T1CKI pins. If the TMR1CS and T1OSCEN bits are cleared (TMR1 reverts to the timer mode and TMR1 oscillator is disabled), then pin PORTB<2:1> will be driven with the value in the data latches.

NOTES:

8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, TACQ, see the PIC® Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL

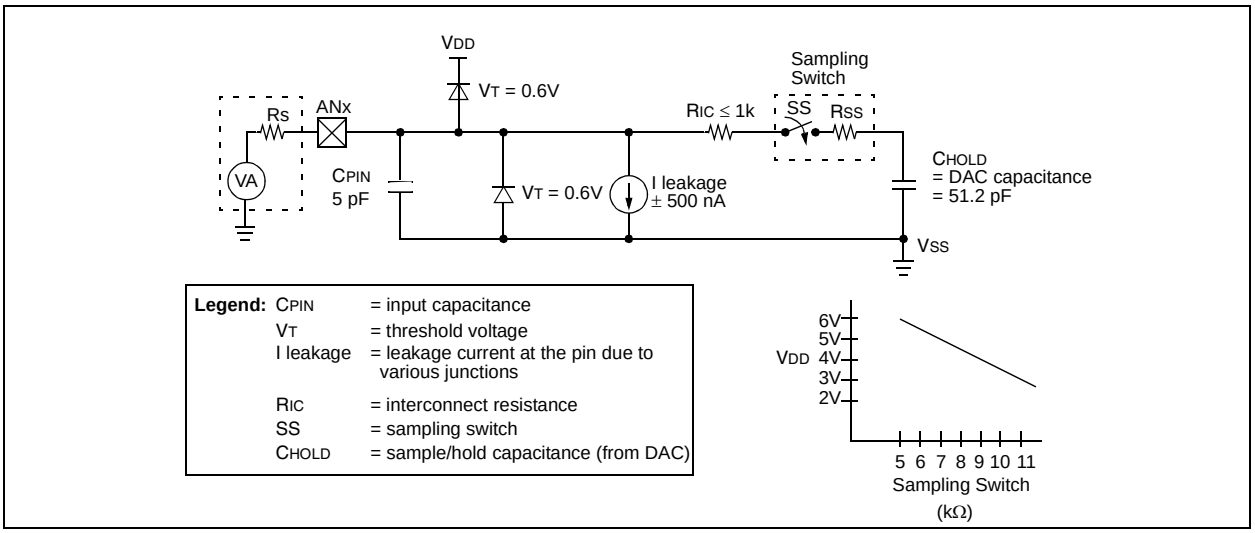


FIGURE 9-1: CONFIGURATION WORD

$\overline{CP1}$	$\overline{CP0}$	$\overline{CP1}$	$\overline{CP0}$	$\overline{CP1}$	$\overline{CP0}$	—	BODEN	$\overline{CP1}$	$\overline{CP0}$	$\overline{PWRTE}$	WDTE	FOSC1	FOSC0
bit13													bit0

Register:CONFIG
Address2007h

bit 13-8, 5-4: **$\overline{CP1}$:$\overline{CP0}$**: Code Protection bits **(2)**
Code Protection for 2K Program memory (PIC16C716)
11 = Programming code protection off
10 = 0400h-07FFh code protected
01 = 0200h-03FFh code protected
00 = 0000h-07FFh code protected

bit 13-8, 5-4:
Code Protection for 1K Program memory bits (PIC16C712)
11 = Programming code protection off
10 = Programming code protection off
01 = 0200h-03FFh code-protected
00 = 0000h-03FFh code-protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit **(1)**
1 = BOR enabled
0 = BOR disabled

bit 3: **$\overline{PWRTE}$**: Power-up Timer Enable bit **(1)**
1 = PWRT disabled
0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{PWRTE}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the $\overline{CP1}$:$\overline{CP0}$ pairs have to be given the same value to enable the code protection scheme listed.

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

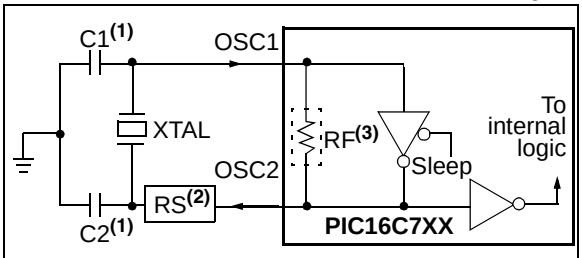
The PIC16CXXX can be operated in four different Oscillator modes. The user can program two Configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 9-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 9-3).

FIGURE 9-2: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 9-1 and Table 9-2 for recommended values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the crystal chosen.

FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

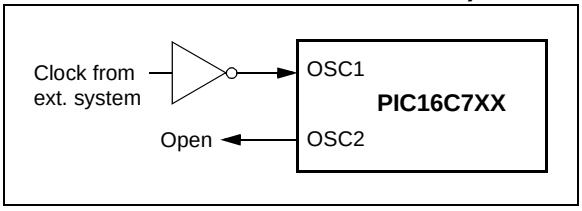


TABLE 9-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-68 pF 15-68 pF	68-100 pF 15-68 pF 15-68 pF
HS	8.0 MHz 16.0 MHz	10-68 pF 10-22 pF	10-68 pF 10-22 pF
These values are for design guidance only. See notes at bottom of page.			

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes at bottom of page.			

Note 1: Recommended values of C1 and C2 are identical to the ranges tested (Table 9-1).
2: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode, as well as XT mode to avoid overdriving crystals with low drive level specification.

9.10.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if bit INTEDG (OPTION_REG<6>) is set, or falling if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the Interrupt Service Routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from Sleep, if bit INTE was set prior to going into Sleep. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See **Section 9.13 "Power-down Mode (Sleep)"** for details on Sleep mode.

9.10.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (**Section 4.0 "Timer0 Module"**)

9.10.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (**Section 3.2 "PORTB and the TRISB Register"**)

9.11 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt, (i.e., W register and STATUS register). This will have to be implemented in software.

Example 9-1 stores and restores the W and STATUS registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Stores the PCLATH register.
d) Executes the Interrupt Service Routine code (User-generated).
e) Restores the STATUS register (and bank select bit).
f) Restores the W and PCLATH registers.

EXAMPLE 9-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
MOVWF    W_TEMP           ;Copy W to TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
CLRF     STATUS           ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
MOVF     PCLATH, W        ;Only required if using pages 1, 2 and/or 3
MOVWF    PCLATH_TEMP      ;Save PCLATH into W
CLRF     PCLATH           ;Page zero, regardless of current page
BCF      STATUS, IRP      ;Return to Bank 0
MOVF     FSR, W           ;Copy FSR to W
MOVWF    FSR_TEMP         ;Copy FSR from W to FSR_TEMP
:
:(ISR)
:
MOVF     PCLATH_TEMP, W   ;Restore PCLATH
MOVWF    PCLATH           ;Move W into PCLATH
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                          ;(sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
```

9.12 Watchdog Timer (WDT)

The Watchdog Timer is as a free running, on-chip, RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device have been stopped, for example, by execution of a SLEEP instruction.

During normal operation, a WDT Time-out generates a device Reset (Watchdog Timer Reset). If the device is in Sleep mode, a WDT Time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The $\overline{TO}$ bit in the STATUS register will be cleared upon a Watchdog Timer Time-out.

The WDT can be permanently disabled by clearing Configuration bit WDTE (**Section 9.1 "Configuration Bits"**).

WDT time-out period values may be found in the Electrical Specifications section under TWDT (parameter #31). Values for the WDT prescaler (actually a postscaler, but shared with the Timer0 prescaler) may be assigned using the OPTION_REG register.

Note:	The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset condition.

.

Note:	When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 9-15: WATCHDOG TIMER BLOCK DIAGRAM

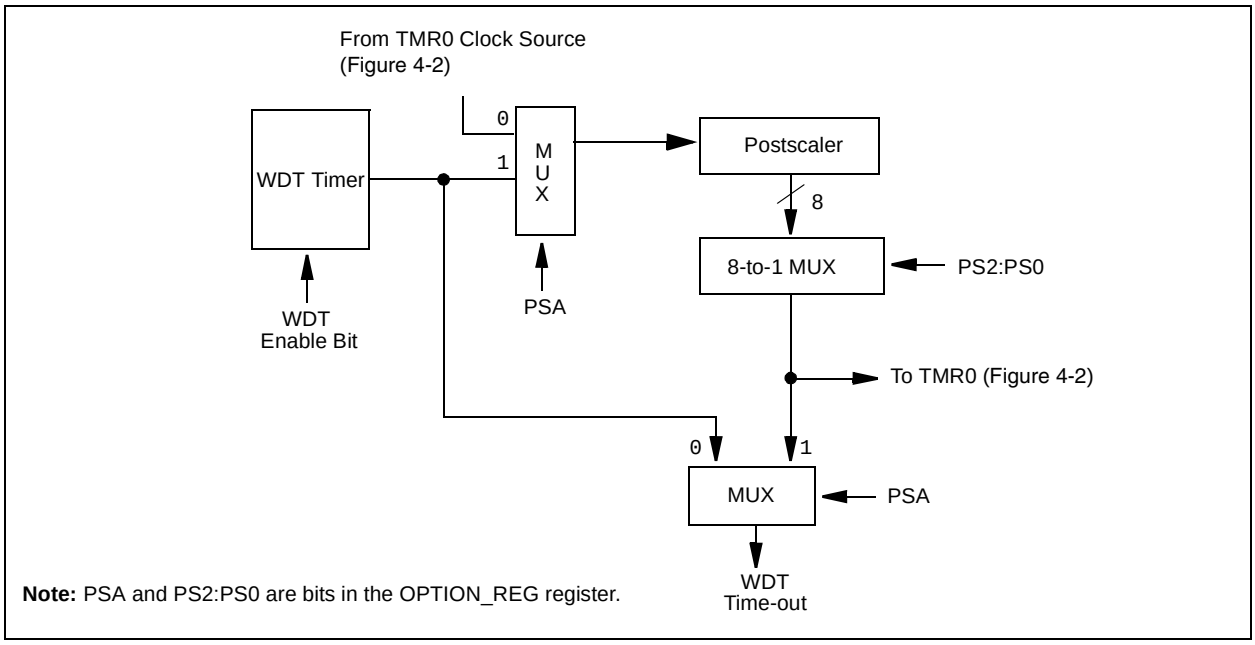


FIGURE 9-16: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bits 13:8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	**(1)**	—	BODEN(1)	$\overline{CP1}$	$\overline{CP0}$	$\overline{PWRTE}$(1)	WDTE	FOSC1	FOSC0
81h	OPTION_REG	N/A	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer.
Note 1: See Figure 9-1 for operation of these bits.

10.0 INSTRUCTION SET SUMMARY

Each PIC16CXXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXXX instruction set summary in Table 10-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
PC	Program Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
Z	Zero bit
DC	Digit Carry bit
C	Carry bit

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 10-2 lists the instructions recognized by the MPASM assembler.

Figure 10-1 shows the general formats that the instructions can have.

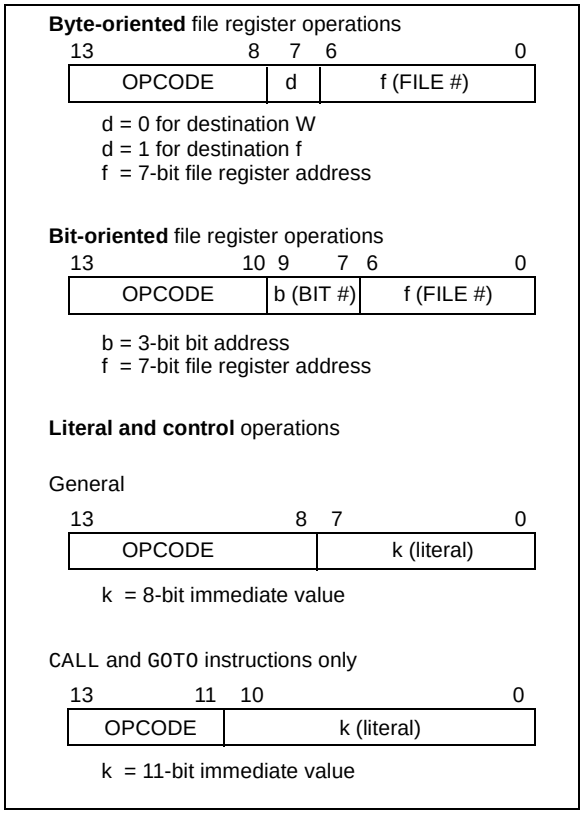
Note: To maintain upward compatibility with future PIC16CXXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



A description of each instruction is available in the PIC® Mid-Range Reference Manual, (DS33023).

12.4 AC (Timing) Characteristics

12.4.1 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

12.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 12-1 apply to all timing specifications, unless otherwise noted. Figure 12-3 specifies the load conditions for the timing specifications.

TABLE 12-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

	Standard Operating Conditions (unless otherwise stated)				
	Operating temperature	0°C	≤ TA ≤	+70°C	for commercial
		-40°C	≤ TA ≤	+85°C	for industrial
		-40°C	≤ TA ≤	+125°C	for extended
AC CHARACTERISTICS	Operating voltage VDD range as described in DC spec **Section 12.1 "DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)"** and **Section 12.2 "DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)"**.				
	LC parts operate for commercial/industrial temp's only.				

FIGURE 12-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

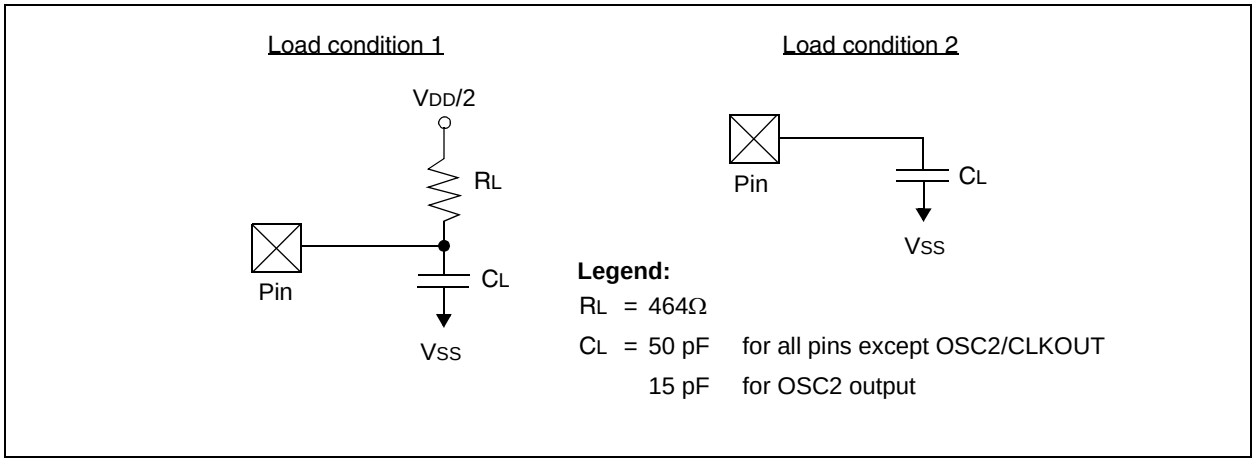
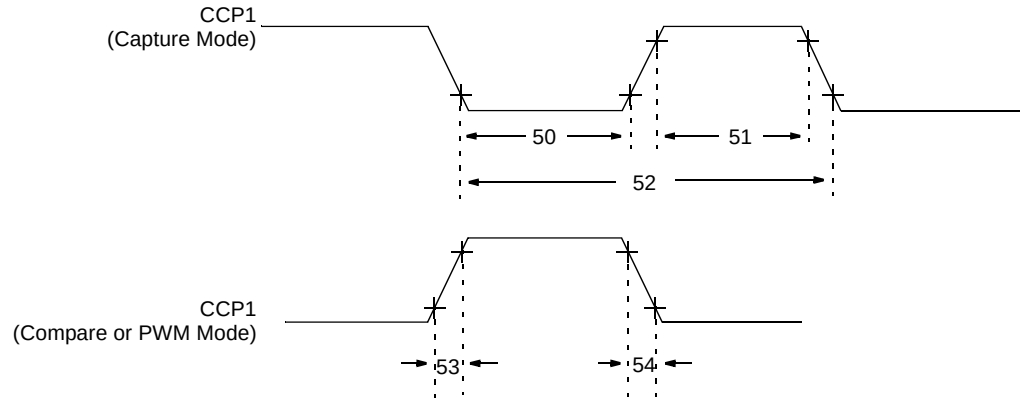


FIGURE 12-9: CAPTURE/COMPARE/PWM TIMINGS



Note: Refer to Figure 12-3 for load conditions.

TABLE 12-6: CAPTURE/COMPARE/PWM REQUIREMENTS

Param No.	Sym.	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard	10	—	—	ns	
				Extended (LC)	20	—	—	ns	
51*	TccH	CCP1 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard	10	—	—	ns	
				Extended (LC)	20	—	—	ns	
52*	TccP	CCP1 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 output rise time		Standard	—	10	25	ns	
				Extended (LC)	—	25	45	ns	
54*	TccF	CCP1 output fall time		Standard	—	10	25	ns	
				Extended (LC)	—	25	45	ns	

* These parameters are characterized but not tested.

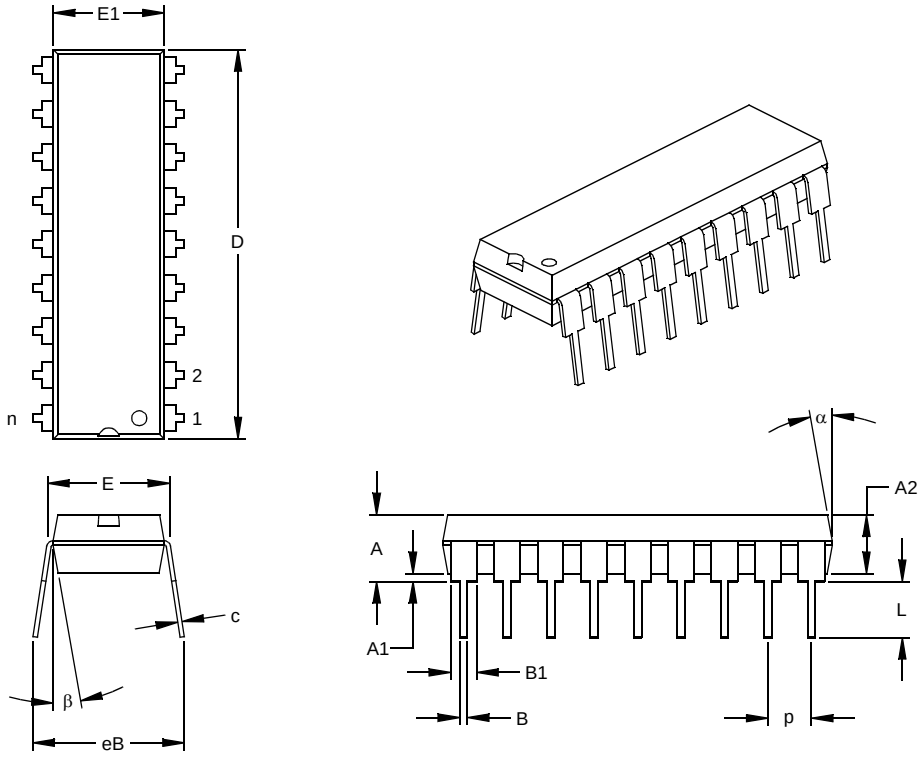
† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

13.2 Package Details

The following sections give the technical details of the packages.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



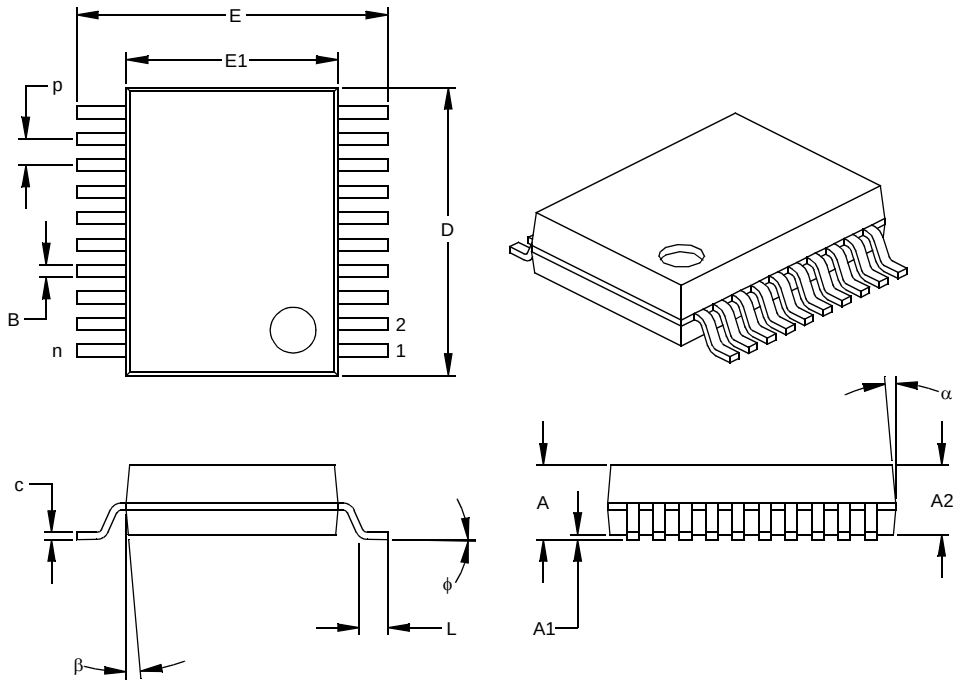
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

M

O

P

W

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

TO: Technical Publications Manager Total Pages Sent _____

RE: Reader Response

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___ Y ___ N

Device: PIC16C712/716 Literature Number: DS41106C

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

NOTES: